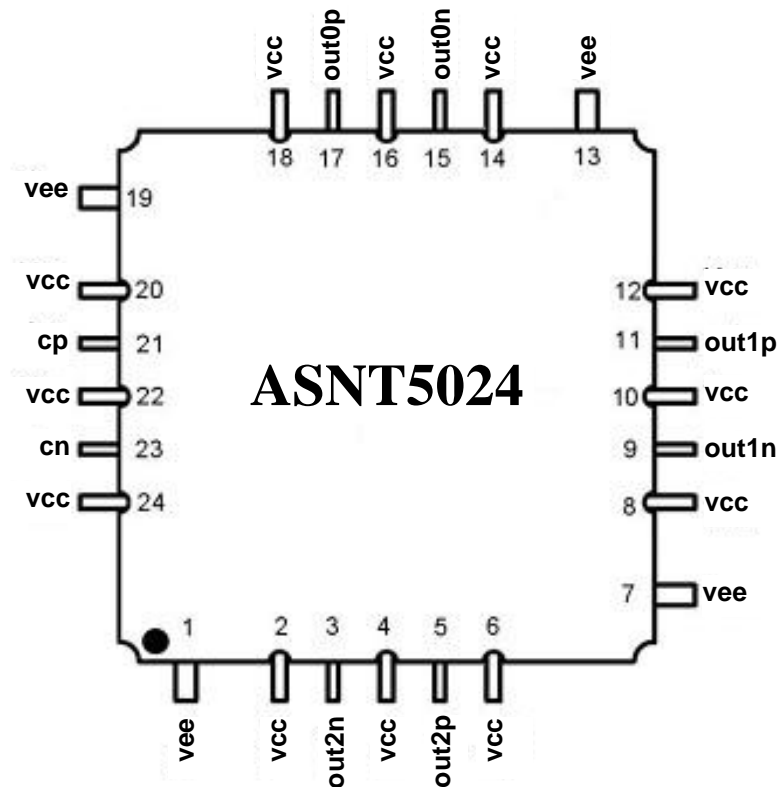




ASNT5024-KMC DC-28Gbps/17GHz Signal Distributor 1-to-3

- High-speed broadband Data/Clock Amplifier and Distributor
- Exhibits low jitter and limited temperature variation over industrial temperature range
- One input differential signal port and three differential amplified output signal ports
- Matched phase delays for all outputs
- Fully differential CML input interface
- Fully differential CML output interfaces with 600mV single-ended swing
- Single +3.3V or -3.3V power supply
- Power consumption: 780mW
- Fabricated in SiGe for high performance, yield, and reliability
- Custom CQFP 24-pin package



DESCRIPTION

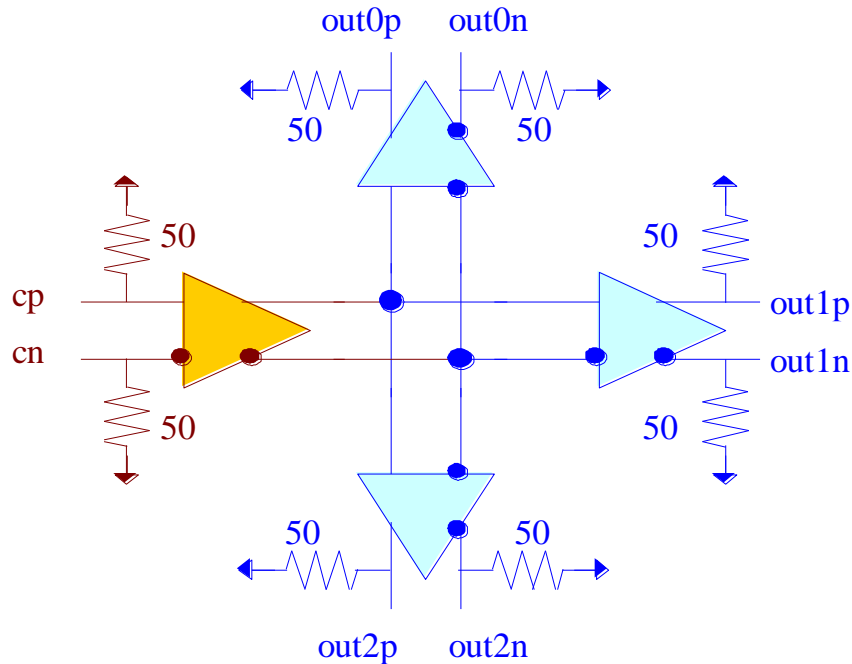


Fig. 1. Functional Block Diagram

The temperature stable ASNT5024-KMC SiGe IC provides active broadband data/clock signal splitting, and is intended for use in high-speed measurement / test equipment. The IC shown in Fig. 1 can deliver three phase-matched copies of the broadband data/clock input signal *cp/cn* to three high-speed differential outputs *out0p/out0n*, *out1p/out1n*, *out2p/out2n*.

The part's I/O's support the CML logic interface with on chip 50Ω termination to *vcc* and may be used differentially, AC/DC coupled, single-ended, or in any combination (see also POWER SUPPLY CONFIGURATION). In the DC-coupling mode, the input signal's common mode voltage should comply with the specifications shown in ELECTRICAL CHARACTERISTICS. In the AC-coupling mode, the input termination provides the required common mode voltage automatically. The differential DC signaling mode is recommended for optimal performance.

POWER SUPPLY CONFIGURATION

The part can operate with either negative supply (*vcc* = 0.0V = ground and *vee* = -3.3V), or positive supply (*vcc* = +3.3V and *vee* = 0.0V = ground). In case of the positive supply, all I/Os need AC termination when connected to any devices with 50Ω termination to ground. Different PCB layouts will be needed for each different power supply combination.

All the characteristics detailed below assume *vcc* = 0.0V and *vee* = -3.3V.



ABSOLUTE MAXIMUM RATINGS

Caution: Exceeding the absolute maximum ratings shown in Table 1 may cause damage to this product and/or lead to reduced reliability. Functional performance is specified over the recommended operating conditions for power supply and temperature only. AC and DC device characteristics at or beyond the absolute maximum ratings are not assumed or implied. All min and max voltage limits are referenced to ground.

Table 1. Absolute Maximum Ratings

Parameter	Min	Max	Units
Supply Voltage (vee)		-3.6	V
Power Consumption		0.86	W
RF Input Voltage Swing (SE)		1.0	V
Case Temperature		+90	°C
Storage Temperature	-40	+100	°C
Operational Humidity	10	98	%
Storage Humidity	10	98	%

TERMINAL FUNCTIONS

TERMINAL			DESCRIPTION
Name	No.	Type	
High-Speed I/Os			
cp	21	CML input	Differential high speed data/clock inputs with internal SE 50Ohm termination to VCC
cn	23		
out0p	17	CML output	Differential high speed data/clock outputs with internal SE 50Ohm termination to VCC. Require external SE 50Ohm termination to VCC
out0n	15		
out1p	11	CML output	Differential high speed data/clock outputs with internal SE 50Ohm termination to VCC. Require external SE 50Ohm termination to VCC
out1n	9		
out2p	5	CML output	Differential high speed data/clock outputs with internal SE 50Ohm termination to VCC. Require external SE 50Ohm termination to VCC
out2n	3		
Supply and Termination Voltages			
Name	Description		Pin Number
vcc	Positive power supply (+3.3V or 0)		2, 4, 6, 8, 10, 12, 14, 16, 18, 20, 22, 24
vee	Negative power supply (0V or -3.3V)		1, 7, 13, 19



ELECTRICAL CHARACTERISTICS

PARAMETER	MIN	TYP	MAX	UNIT	COMMENTS
General Parameters					
v _{ee}	-3.1	-3.3	-3.5	V	±6%
v _{cc}		0.0		V	External ground
I _{vee}		235		mA	
Power consumption		780		mW	
Junction temperature	-40	25	125	°C	
HS Input Data/Clock (cp/cn)					
Data Rate	DC		28	Gbps	
Frequency	DC		17	GHz	
Swing	0.05		1.0	V	Differential or SE, p-p
CM Voltage Level	v _{cc} -0.8		v _{cc}	V	Must match for both inputs
HS Output Data/Clock (out0p/out0n, out1p/out1n, out2p/out2n)					
Data Rate	DC		28	Gbps	
Frequency	DC		17	GHz	
Latency		64		ps	From any input to any output
Phase mismatch			2	ps	Between any two SE outputs
Logic "1" level		v _{cc}		V	
Logic "0" level		v _{cc} -0.6		V	With external 50Ωm DC termination
Rise/Fall times	15		19	ps	20%-80%
Additive Jitter			5	ps	Peak-to-peak
Duty cycle	45	50	55	%	For clock signal

PACKAGE INFORMATION

The chip die is housed in a custom 24-pin CQFP package shown in Fig. 2. The package provides a center heat slug located on its back side to be used for heat dissipation. ADSANTEC recommends for this section to be soldered to the v_{cc} plain, which is ground for a negative supply, or power for a positive supply.

The part's identification label is ASNT5024-KMC. The first 8 characters of the name before the dash identify the bare die including general circuit family, fabrication technology, specific circuit type, and part version while the 3 characters after the dash represent the package's manufacturer, type, and pin out count.

This device complies with the Restriction of Hazardous Substances (RoHS) per 2011/65/EU for all ten substances.

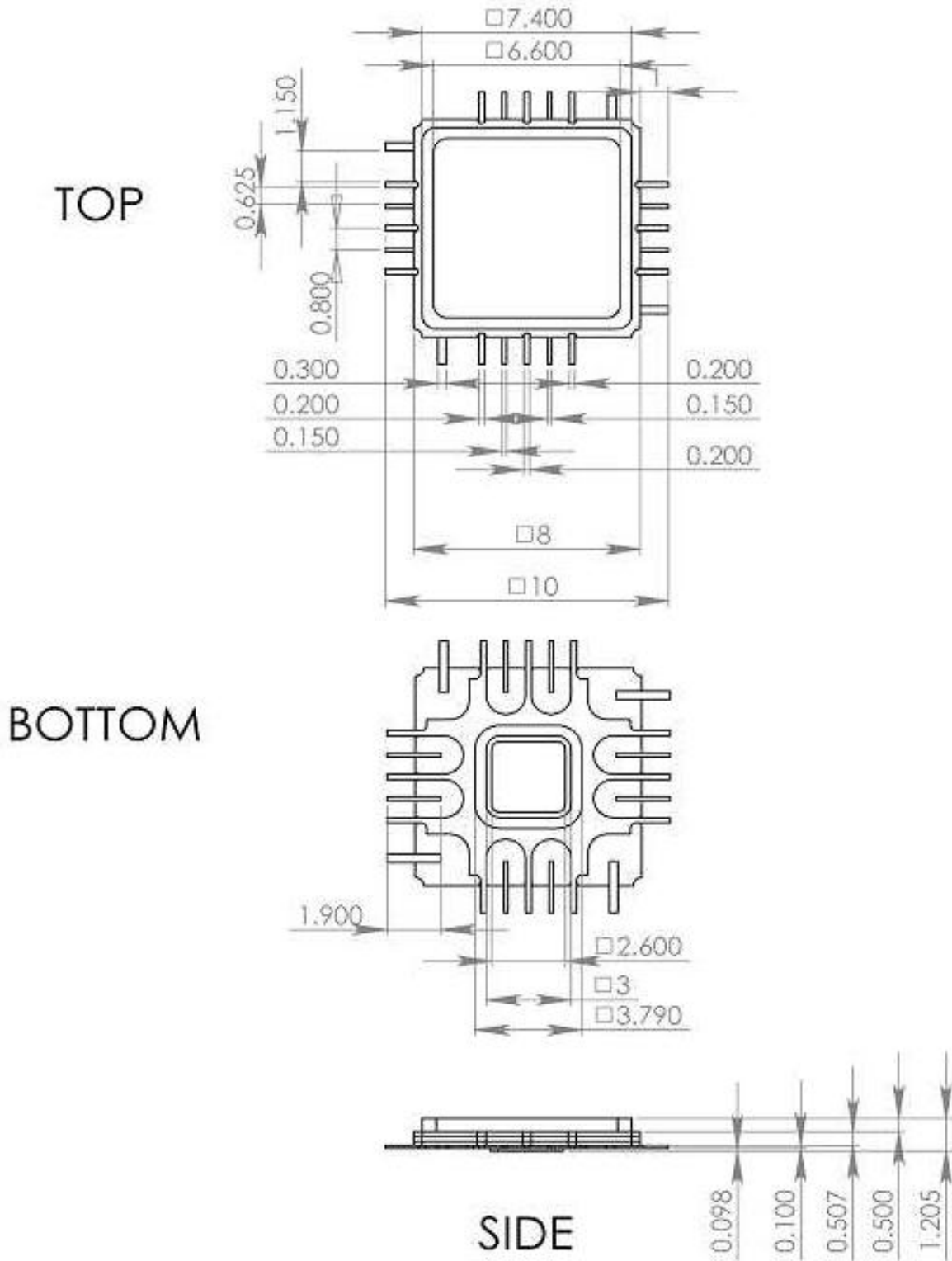


Fig. 2. CQFP 24-Pin Package Drawing (All Dimensions in mm)



REVISION HISTORY

Revision	Date	Changes
4.3.2	05-2020	Updated Package Information
4.2.2	07-2019	Updated Letterhead
4.2.1	08-2018	Added latency specifications Updated package information section
4.1.1	03-2013	Added phase mismatch specifications Updated description
4.0.1	02-2013	Revised title Revised package pin out drawing Revised description Revised power supply configuration Revised absolute maximum ratings Revised terminal functions Revised electrical characteristics Revised package information Added mechanical drawing Format correction
3.1	02-2012	Revised pin out drawing Revised power supply configuration section Revised package information section
3.0	01-2012	Added power supply configuration text Added absolute maximum ratings table Revised electrical characteristics section Revised package information section
2.0	02-2009	Revised electrical characteristics section Revised package information section
1.0	01-2009	First release